

FOR PRECISION ANALOG, SENSORS, AND POWER APPLICATIONS

Your Solution for Automotive and Precision Applications

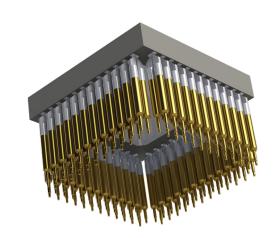
Looking for solutions in the highly-competitive automotive and commercial market? You can rely on Johnstech to provide a high-performance, quality solution. Johnstech has taken all the best features found throughout the Spring Probe world and combined them into our designs.

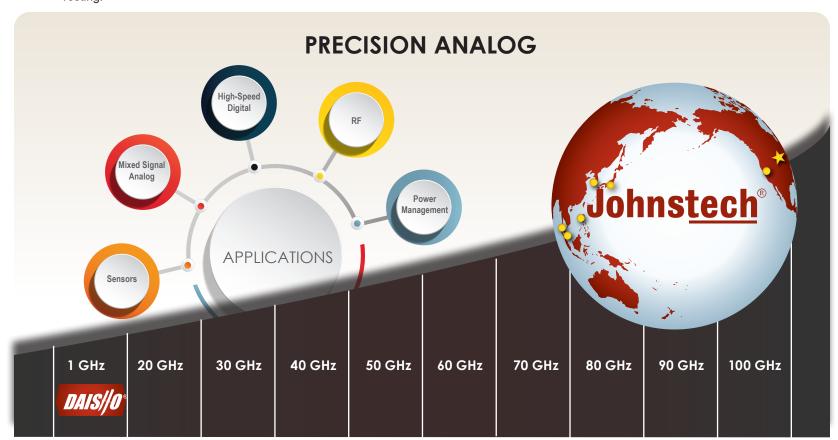
- Suitable for BGA, QFN, Leaded, and WLCSP applications.
 - o Blade BGA, QFN, WLCSP, and Leaded
 - o Fine QFN
 - o Knife-Edge BGA, WLCSP, and Leaded
- The DAISHO is designed in a single-ended architecture to minimize Cres variability.
- Fully user serviceable contactor architecture individually replaceable probes
- · Pd alloy tips for easy cleaning
- Compatible with a floating alignment plate for accuracy

A lot of experience and care went into the design of these probes to provide our customers with the best features. Johnstech studied several hundred BGA packages to understand ball diameters and heights that are most prevalent. We were able to optimize the tip geometry based on this exhaustive study of the market.

All Contactors will be available for Engineering test/characterization with a Manual Actuator and are ready for high-volume Automated Testing.

FEATURES & BENEFITS						
LARGE BALL COUNT	Capable of >1,000					
PITCH	QFN ≥ 0.3mm; WLCSP and BGA ≥ 0.35mm					
TEMPERATURE	-65°C to 175°C					
CURRENT CARRY CAPABILITY @1%; @100%	19.3A, 1.93A					
CONTACT RESISTANCE (mΩ)	40					
HIGH VOLTAGE CAPABLE (MATERIAL)	16.5kV @ 0.5mm 1.65 pA Leakage Current					







Electrical Specifications

Probe Size/Pitch (mm)	Contact Resistance* (mΩ)	CCC 100% Duty Cycle (Amps)	CCC 1% DC RMS (Amps)	Loop Inductance (nH)
0.3 QFN; 0.35 BGA	80	1.35	13.50	0.85
0.4 QFN	40	1.93	19.30	1.1
0.4 BGA/Leaded	40	1.93	19.30	1.1

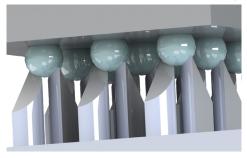
Results shown are typical for one size and configuration shown here. These charts are representative data. Please contact your Johnstech Sales Representative for additional specifications for specific test applications

*Contact Resistance depends on maintenance, cleaning and device materials. The values shown are measured average based on a new probe.

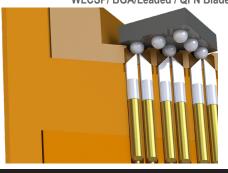
Mechanical Specifications

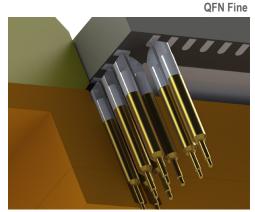
Probe Size/ Pitch (mm)	Minimum BGA/ WLCSP Ball Pitch (mm)	Test Height (mm)	Uncom- pressed Free Length FL (mm)	DUT Side Compliance (mm)	Total Stroke (mm)	Force at Test (g)	Minimum DUT Force-Sense Tip-Tip Spacing TT (mm)	Minimum PCB Force-Sense Pad Center Spacing P (mm)	Barrel Diameter B (mm)
0.3 QFN; 0.35 BGA	0.35	3.0	3.25	0.15	0.25	15	.070	0.28	0.21
0.4 QFN	N/A	3.22	3.62	0.30	0.40	20	0.70	0.40	0.33
0.4 Leaded	0.65	3.41	3.81	0.30	0.40	20	0.70	0.40	0.33

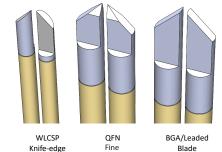
WLCSP/BGA/Leaded Knife-Edge



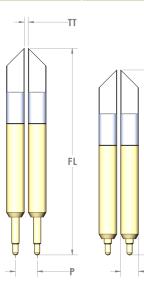
WLCSP/ BGA/Leaded / QFN Blade











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